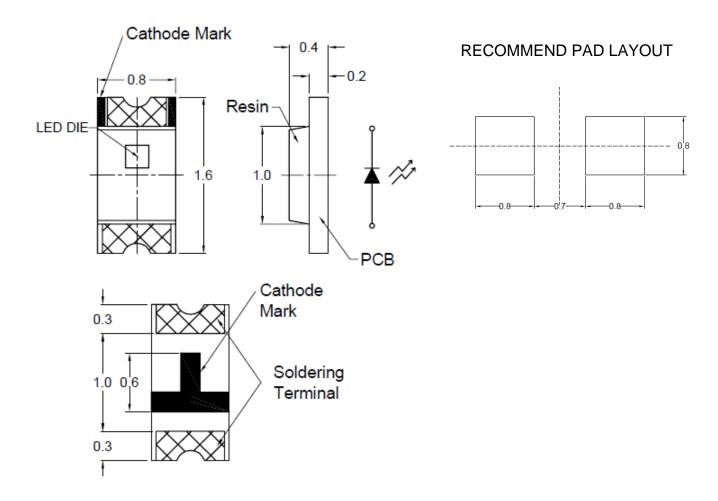


1.6 x 0.8 x 0.4 mm Red SMD LED

### **PACKAGE OUTLINES**



#### NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are  $\pm 0.1$ mm unless otherwise noted.

Chip Material	Chip Emitted	Lens Color	Viewing Angle
AlGalnP	Red	Water Clear	110



1.6 x 0.8 x 0.4 mm Red SMD LED

#### **ABSOLUTE MAXIMUM RATINGS**

(Ta=25°C)

Parameter	Symbol	Value	Unit
Forward current	If	30	mA
Reverse current @ 5V	Ir	10	μΑ
Power dissipation	Pd	72	mW
Operating temperature range	Тор	-40~+85	°C
Storage temperature range	Tstg	-40~+90	°C
Peak pulsing current (1/10 duty f= 10KHz)	lfp	90	mA
Electrostatic Discharge	ESD	2000	V
Soldering Temperature	T <sub>SOL</sub>	Max 260°C for 5 sec Max	

### **OPTICAL-ELECTRICAL CHARACTERISTICS**

(Ta=25°C)

December	Ownell at Canadition		Value			111.74
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Wavelength at peak emission	λpeak	I <sub>F</sub> = 20mA	1	642	1	nm
Spectral half bandwidth	Δλ	I <sub>F</sub> = 20mA	ı	20	ı	nm
Dominant wavelength	λdom	I <sub>F</sub> = 20mA	1	630	-	Nm
Forward Voltage	Vf	I <sub>F</sub> = 20mA	1.5	ı	2.4	V
Luminous intensity	lv	I <sub>F</sub> = 20mA	30	80	-	mcd
Viewing angle at 50% lv	20 ½	I <sub>F</sub> = 20mA	-	110	-	Deg



1.6 x 0.8 x 0.4 mm Red SMD LED

### **Brightness Bin Code**

Group	(mcd) at 20mA		Unit
Group	MIN	MAX	Offic
N	32	50	
Р	50	80	Mad
Q	80	125	Mcd
R	125	200	

### Color Code For Visible SMD

Group	(nm) at 20mA		Unit
Group	MIN	MAX	Offic
29	624	627	
30	627	630	nm
31	630	633	nm
32	633	636	



1.6 x 0.8 x 0.4 mm Red SMD LED

#### **OPTICAL CHARACTERISTIC CURVES**

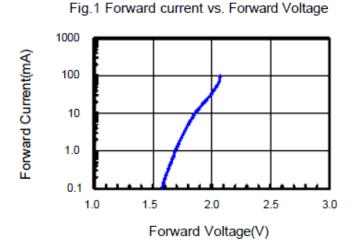


Fig.2 Relative Intensity vs. Forward Current

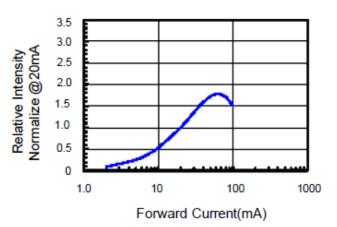


Fig.3 Forward Voltage vs. Temperature

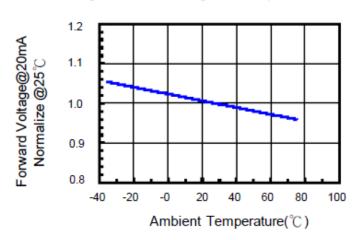


Fig.4 Relative Intensity vs. Temperature

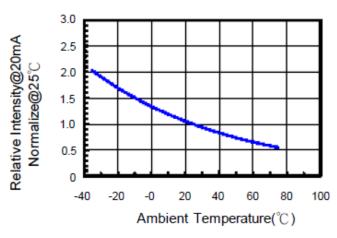


Fig.5 Relative Intensity vs. Wavelength

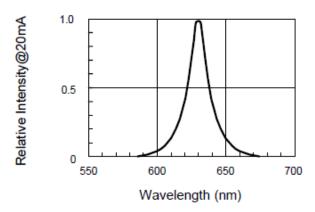
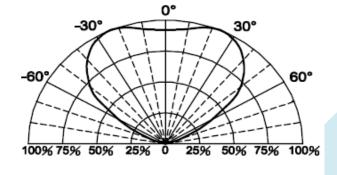


Fig.6 Directive Radiation

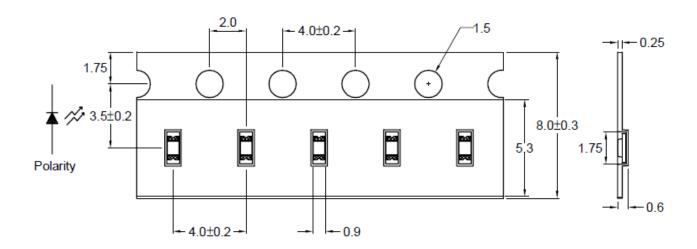


Version 1.0 Date: 08-08-2011

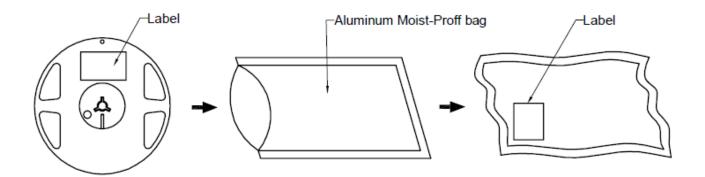


1.6 x 0.8 x 0.4 mm Red SMD LED

### **Dimensions of Tape (Unit: mm)**



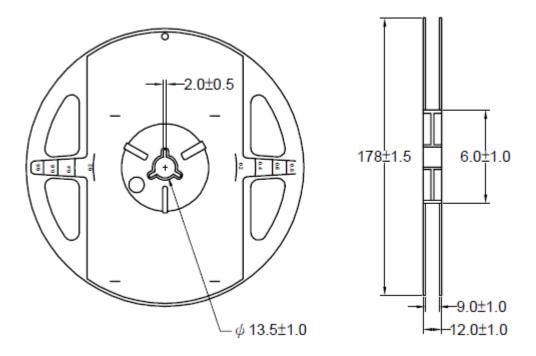
### **PACKAGING SPECIFICATION**





1.6 x 0.8 x 0.4 mm Red SMD LED

#### **REEL DIMENSIONS**



#### Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 4,000pcs/Reel

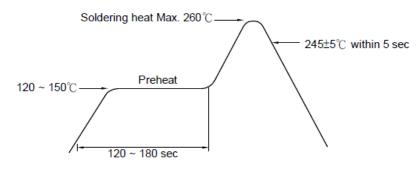
Version 1.0 Date: 08-08-2011



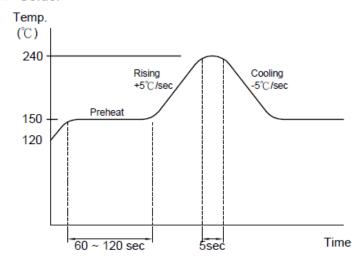
1.6 x 0.8 x 0.4 mm Red SMD LED

### **Recommended Soldering Conditions**

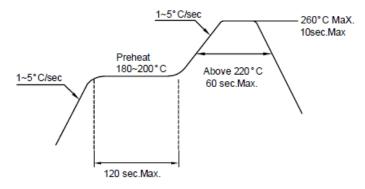
- Hand Solder
   Basic spec is ≤ 280°C 3 sec one time only.
- 2. Wave Solder



#### 3-1. LEAD Reflow Solder



#### 3-2 PB-Free Reflow Solder



Reflow Soldering should not be done more than two times.



1.6 x 0.8 x 0.4 mm Red SMD LED

#### Precautions For Use:

#### Storage time:

- 1. The operation of Temperatures and RH are : 5 °C ~35°C ,RH60%.
- 2.Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year(from production date).
- 3.If opened more than one week in an atmosphere 5  $^{\circ}$ C  $\sim$  35 $^{\circ}$ C,RH60%, they should be treated at 60  $^{\circ}$ C±5 $^{\circ}$ C fo r 15hrs.

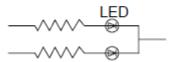
#### Drive Method:

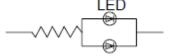
LED is a current operated device, and therefore, requirer some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in series with the LED.

Consider worst case voltage variations than could occur across the current limiting resistor. The forwrd current should not be allowed to change by more than 40 % of its desired value.

Circuit model A







- (A) Recommended circuit.
- (B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

### ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing these LED. All devices, equipment and machinery must be properly grounded.



1.6 x 0.8 x 0.4 mm Red SMD LED

### **RELIABILITY TEST**

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operating Life Test	1.Ta=Under Room Temperature As Per Data Sheet Maximum Rating. 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-750D: 1026 MIL-STD-883D: 1005 JIS C 7021: B-1
	High Temperature Storage Test	1.Ta=105°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-883D:1008 JIS C 7021: B-10
	Low Temperature Storage Test	1.Ta=-40°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	JIS C 7021: B-12
	High Temperature High Humidity Storage Test	1.Ta=65°C±5°C 2.RH=90%~95% 3.t=1000hrs±2hrs	MIL-STD-202F:103B JIS C 7021: B-11
Environmental Test	Thermal Shock Test	1.Ta=105°C±5°C &-40°C±5°C (10min) (10min) 2.total 10 cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1011
	Solderability Test	1.T.Sol=235°C±5°C 2.Immersion time 2±0.5sec 3.Coverage ≥95% of the dipped surface	MIL-STD-202F: 208D MIL-STD-750D: 2026 MIL-STD-883D: 2003 IEC 68 Part 2-20 JIS C 7021: A-2
	Temperature Cycling	1.105°C ~ 25°C ~ -55°C ~ 25°C 30mins 5mins 30mins 5mins 2.10 Cyeles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1010 JIS C 7021: A-4
	IR Reflow	1.T=260°C Max. 10sec.Max. 2. 6 Min	MIL-STD-750D:2031.2 J-STD-020